

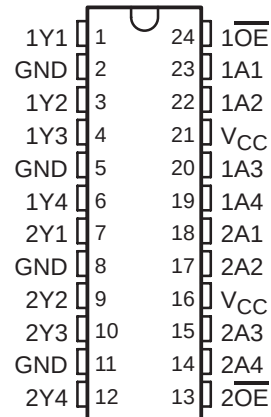
SN64BCT25244

25-Ω OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCBS477 – DECEMBER 1992 – REVISED JANUARY 1994

- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- High-Impedance State During Power Up and Power Down
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model ($C = 200$ pF, $R = 0$)
- Designed to Facilitate Incident-Wave Switching for Line Impedances of 25 Ω or Greater
- Distributed V_{CC} and GND Pins Minimize Noise Generated by the Simultaneous Switching of Outputs
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (NT)

DW OR NT PACKAGE
(TOP VIEW)



description

The SN64BCT25244 is a 25-Ω octal buffer and line driver designed specifically to improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented transceivers.

When the output-enable ($\overline{1OE}$ and $\overline{2OE}$) inputs are low, the device transmits data from the A inputs to the Y outputs. When $\overline{1OE}$ and $\overline{2OE}$ are high, the outputs are in the high-impedance state.

This buffer/driver is capable of sinking 188-mA I_{OL} , which facilitates switching 25-Ω transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more reliable system operation.

The outputs are in a high-impedance state during power up and power down while the supply voltage value is less than approximately 3 V.

The SN64BCT25244 is characterized for operation from -40°C to 85°C and 0°C to 70°C .

FUNCTION TABLE
(each buffer/driver)

INPUTS		OUTPUT Y
$\overline{OE}$	A	
L	H	H
L	L	L
H	X	Z

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



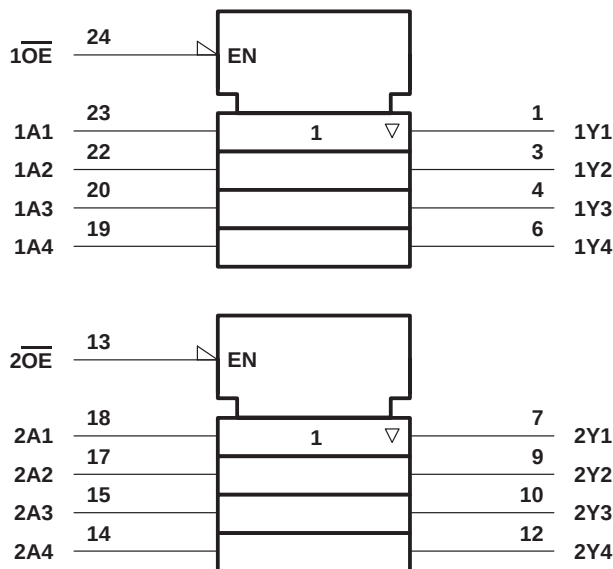
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25-Ω OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

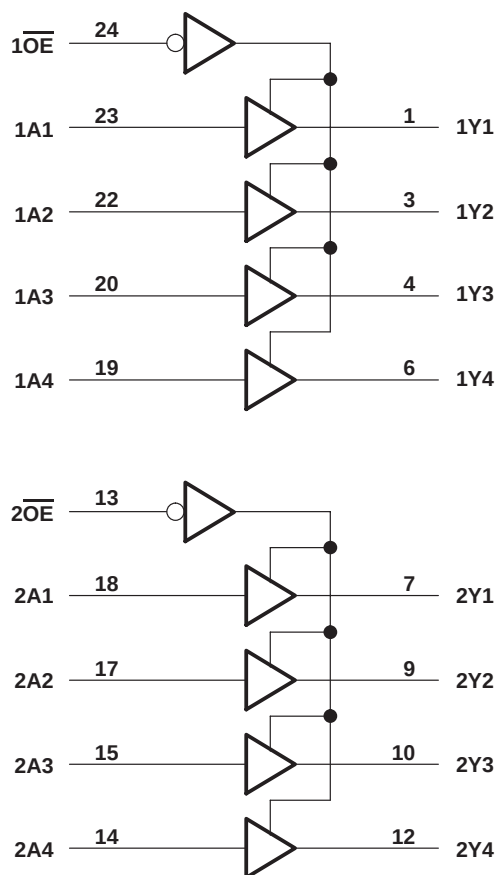
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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input voltage range, V_I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O	–0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O	–0.5 V to V_{CC}
Input clamp current, I_{IK} ($V_I < 0$)	–30 mA
Current into any output in the low state, I_O	376 mA
Operating free-air temperature range	–40°C to 85°C
Storage temperature range	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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25-Ω OCTAL BUFFER/DRIVER
WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{IH}	High-level input voltage	2			V
V _{IL}	Low-level input voltage			0.8	V
I _{IK}	Input clamp current			–18	mA
I _{OH}	High-level output current			–80	mA
I _{OL}	Low-level output current			188	mA
T _A	Operating free-air temperature	–40		85	°C

NOTE 2: Unused or floating inputs must be held high or low.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
V _{IK}	V _{CC} = 4.5 V,	I _I = –18 mA			–1.2	V
V _{OH}	V _{CC} = 4.75 V,	I _{OH} = –3 mA	2.7			V
	V _{CC} = 4.5 V,	I _{OH} = –80 mA	2			
V _{OL}	V _{CC} = 4.5 V	I _{OL} = 94 mA	0.42	0.55		V
		I _{OL} = 188 mA		0.7		
I _{OZ}	V _{CC} = 0 to 2.3 V (power up)	V _O = 2.7 V or 0.5 V, $\overline{\text{OE}}$ at 0.8 V		±50		μA
	V _{CC} = 2.3 to 0 (power down)			±50		
I _I	V _{CC} = 5.5 V,	V _I = 5.5 V			0.1	mA
I _{IH}	V _{CC} = 5.5 V,	V _I = 2.7 V			20	μA
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.5 V			–0.6	mA
I _{OZH}	V _{CC} = 5.5 V,	V _O = 2.7 V			50	μA
I _{OZL}	V _{CC} = 5.5 V,	V _O = 0.5 V			–50	μA
I _{CCL}	V _{CC} = 5.5 V,	Outputs open		90	119	mA
I _{CCH}	V _{CC} = 5.5 V,	Outputs open		59	78	mA
I _{CCZ}	V _{CC} = 5.5 V,	Outputs open		7	11	mA
C _i	V _{CC} = 5 V,	V _I = 2.5 V or 0.5 V		5.5		pF
C _o	V _{CC} = 5 V,	V _O = 2.5 V or 0.5 V		17		pF

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			T _A = –40°C to 85°C		T _A = 0°C to 70°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A	Y	1	3.2	4.9	1	5.6	1	5.5	ns
t _{PHL}			2	4	5.6	2	6.3	2	6	
t _{PZH}	$\overline{\text{OE}}$	Y	3.2	5.6	8.5	3.2	9.7	3.2	9.3	ns
t _{PZL}			3.7	6.3	9.2	3.7	10.4	3.7	10.2	
t _{PHZ}	$\overline{\text{OE}}$	Y	1.6	3.6	5.5	1.6	6.5	1.6	6.3	ns
t _{PLZ}			3.1	5.3	7.8	3.1	9.5	3.1	8.4	

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN64BCT25244DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT25244
SN64BCT25244DW.A	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT25244

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

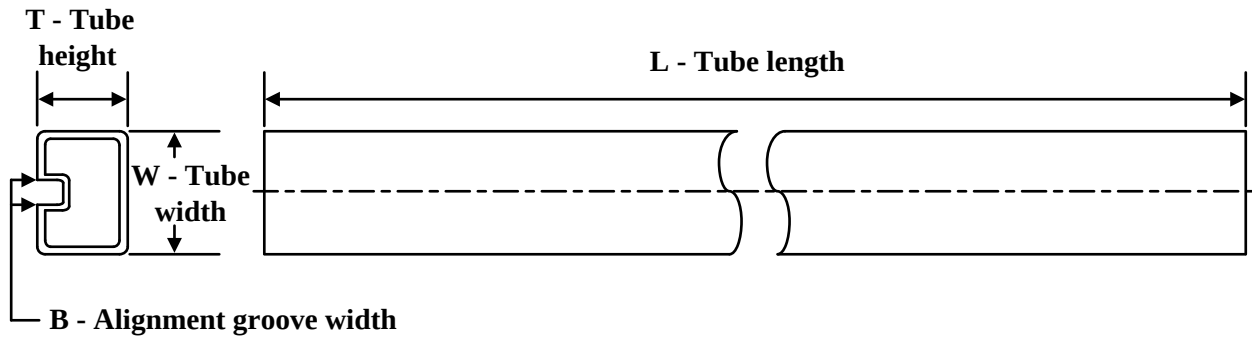
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TUBE

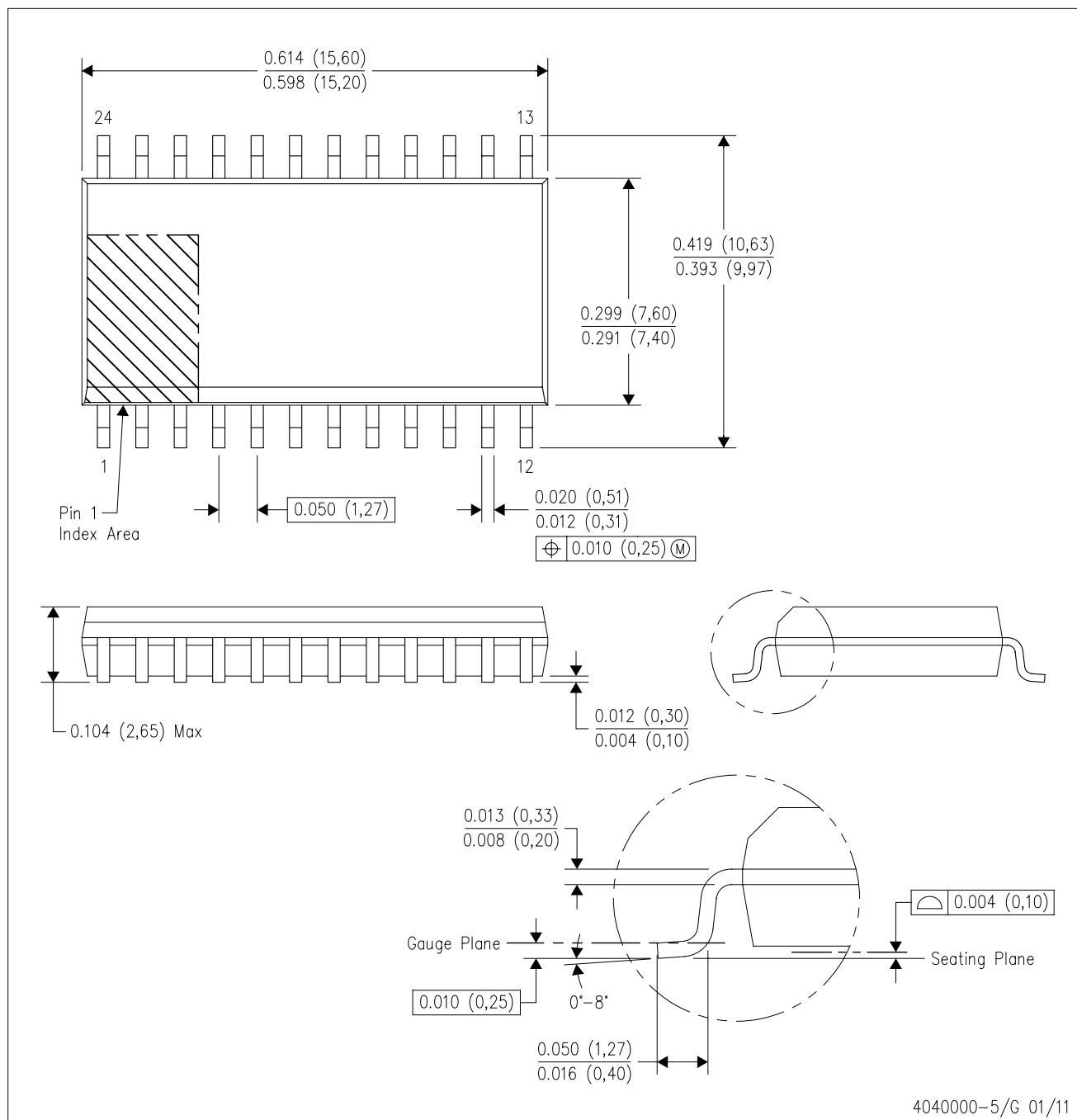


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN64BCT25244DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN64BCT25244DW.A	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



- NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS-013 variation AD.

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